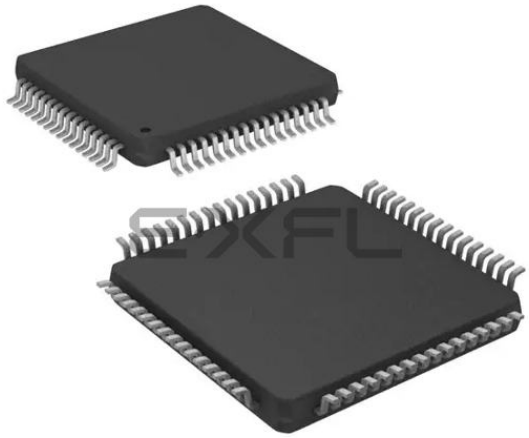
Microchip Technology - PIC24FJ128GA306-I/PT Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj128ga306-i-pt

TABLE 1-2: DEVICE FEATURES FOR THE PIC24FJ128GA310 FAMILY: 80-PIN

Features	PIC24FJ64GA308	PIC24FJ128GA308
Operating Frequency	DC – 32 MHz	
Program Memory (bytes)	64K	128K
Program Memory (instructions)	22,016	44,032
Data Memory (bytes)	8K	
Interrupt Sources (soft vectors/ NMI traps)	65 (61/4)	
I/O Ports	Ports A, B, C, D, E, F, G	
Total I/O Pins	69	
Remappable Pins	40 (31 I/Os, 9 input only)	
Timers: Total Number (16-bit)	5(1)	
32-Bit (from paired 16-bit timers)	2	
Input Capture Channels	7(1)	
Output Compare/PWM Channels	7(1)	
Input Change Notification Interrupt	66	
Serial Communications: UART	4(1)	
SPI (3-wire/4-wire)	2(1)	
I^2C™	2	
Digital Signal Modulator	Yes	
Parallel Communications (EPMP/PSP)	Yes	
JTAG Boundary Scan	Yes	
12/10-Bit Analog-to-Digital Converter (ADC) Module (input channels)	16	
Analog Comparators	3	
CTMU Interface	Yes	
LCD Controller (available pixels)	368 (46 SEG x 8 COM)	
Resets (and Delays)	Core POR, VDD POR, VBAT POR, BOR, RESET Instruction, $\overline{MCLR}$, WDT, Illegal Opcode, REPEAT Instruction, Hardware Traps, Configuration Word Mismatch (OST, PLL Lock)	
Instruction Set	76 Base Instructions, Multiple Addressing Mode Variations	
Packages	80-Pin TQFP and QFN	

Note 1: Peripherals are accessible through remappable pins.

2.4 Voltage Regulator Pin (VCAP)

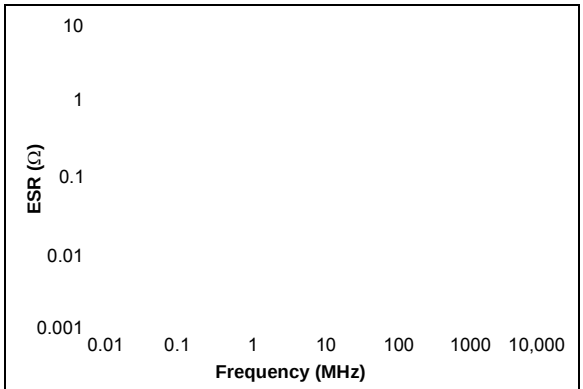
A low-ESR (< 5Ω) capacitor is required on the VCAP pin to stabilize the output voltage of the on-chip voltage regulator. The VCAP pin must not be connected to VDD and must use a capacitor of 10 µF connected to ground. The type can be ceramic or tantalum. Suitable examples of capacitors are shown in Table 2-1. Capacitors with equivalent specification can be used.

The placement of this capacitor should be close to VCAP. It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to **Section 32.0 "Electrical Characteristics"** for additional information.

Designers may use Figure 2-3 to evaluate ESR equivalence of candidate devices.

Refer to **Section 29.2 "On-Chip Voltage Regulator"** for details on connecting and using the on-chip regulator.

FIGURE 2-3: FREQUENCY vs. ESR PERFORMANCE FOR SUGGESTED VCAP



Note: Typical data measurement at +25°C, 0V DC bias.

TABLE 2-1: SUITABLE CAPACITOR EQUIVALENTS

Make	Part #	Nominal Capacitance	Base Tolerance	Rated Voltage	Temp. Range
TDK	C3216X7R1C106K	10 µF	±10%	16V	-55 to +125ºC
TDK	C3216X5R1C106K	10 µF	±10%	16V	-55 to +85ºC
Panasonic	ECJ-3YX1C106K	10 µF	±10%	16V	-55 to +125ºC
Panasonic	ECJ-4YB1C106K	10 µF	±10%	16V	-55 to +85ºC
Murata	GRM32DR71C106KA01L	10 µF	±10%	16V	-55 to +125ºC
Murata	GRM31CR61C106KC31L	10 µF	±10%	16V	-55 to +85ºC

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

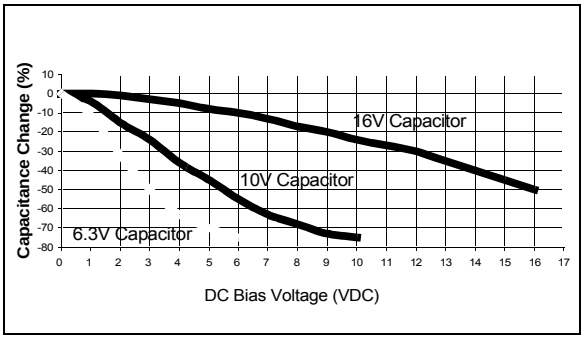
Typical low-cost, 10 μF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R), or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 μF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

Typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating, so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at 16V for the 2.5V or 1.8V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming (ICSP) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

For device emulation, ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 30.0 "Development Support"**.

4.2.5 EXTENDED DATA SPACE (EDS)

The Extended Data Space (EDS) allows PIC24F devices to address a much larger range of data than would otherwise be possible with a 16-bit address range. EDS includes any additional internal data memory not directly accessible by the lower 32-Kbyte data address space, and any external memory through EPMP.

In addition, EDS also allows read access to the program memory space. This feature is called Program Space Visibility (PSV) and is discussed in detail in **Section 4.3.3 "Reading Data from Program Memory Using EDS"**.

Figure 4-4 displays the entire EDS space. The EDS is organized as pages, called EDS pages, with one page equal to size of the EDS window (32 Kbytes). A particular EDS page is selected through the Data Space Read register (DSRPAG) or Data Space Write register (DSWPAG). For PSV, only the DSRPAG register is used. The combination of the DSRPAG register value and the 16-bit wide data address forms a 24-bit Effective Address (EA).

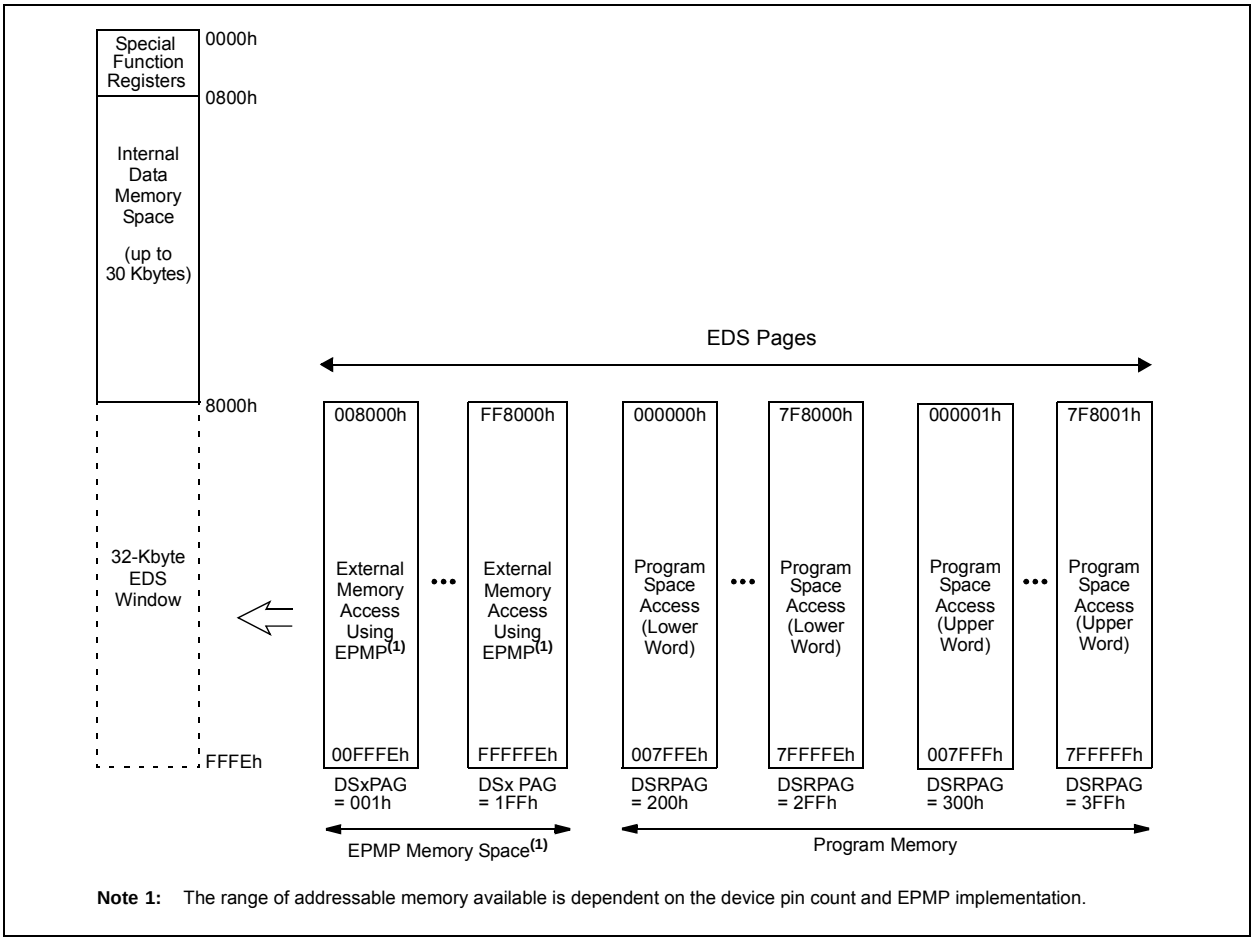
The data addressing range of PIC24FJ128GA310 family devices depends on the version of the Enhanced Parallel Master Port implemented on a particular device; this is in turn a function of device pin count. Table 4-35 lists the total memory accessible by each of the devices in this family. For more details on accessing external memory using EPMP, refer to **"Enhanced Parallel Master Port (EPMP)"** (DS39730) in the *"dsPIC33/PIC24 Family Reference Manual"*.

TABLE 4-35: TOTAL ACCESSIBLE DATA MEMORY

Family	Internal RAM	External RAM Access Using EPMP
PIC24FJXXXGA310	8K	Up to 16 MB
PIC24FJXXXGA308	8K	Up to 64K
PIC24FJXXXGA306	8K	Up to 64K

Note: Accessing Page 0 in the EDS window will generate an address error trap as Page 0 is the base data memory (data locations, 0800h to 7FFFh, in the lower Data Space).

FIGURE 4-4: EXTENDED DATA SPACE



Note 1: The range of addressable memory available is dependent on the device pin count and EPMP implementation.

The CORCON register contains the IPL3 bit, which together with the IPL<2:0> bits, indicate the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

The interrupt controller has the Interrupt Controller Test register, INTTREG, which displays the status of the interrupt controller. When an interrupt request occurs, it's associated vector number and the new Interrupt Priority Level are latched into INTTREG. This information can be used to determine a specific interrupt source if a generic ISR is used for multiple vectors (such as when ISR remapping is used in bootloader applications) or to check if another interrupt is pending while in an ISR.

All interrupt registers are described in Register 8-1 through Register 8-44 in the succeeding pages.

REGISTER 8-1: SR: ALU STATUS REGISTER (IN CPU)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	DC(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2,3)	IPL1(2,3)	IPL0(2,3)	RA(1)	N(1)	OV(1)	Z(1)	C(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: See Register 3-1 for the description of the remaining bits (bits 8, 4, 3, 2, 1 and 0) that are not dedicated to interrupt control functions.

2: The IPLx bits are concatenated with the IPL3 (CORCON<3>) bit to form the CPU Interrupt Priority Level. The value in parentheses indicates the Interrupt Priority Level if IPL3 = 1.

3: The IPLx Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

REGISTER 8-14: IEC1: INTERRUPT ENABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U2TXIE	U2RXIE	INT2IE(1)	T5IE	T4IE	OC4IE	OC3IE	DMA2IE
bit 15							bit 8

U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC7IE	—	INT1IE(1)	CNIE	CMIE	MI2C1IE	SI2C1IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **U2TXIE:** UART2 Transmitter Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 14 **U2RXIE:** UART2 Receiver Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 13 **INT2IE:** External Interrupt 2 Enable bit(1)
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 12 **T5IE:** Timer5 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 11 **T4IE:** Timer4 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 10 **OC4IE:** Output Compare Channel 4 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 9 **OC3IE:** Output Compare Channel 3 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 8 **DMA2IE:** DMA Channel 2 Interrupt Flag Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 7 **Unimplemented:** Read as '0'

bit 6 **IC7IE:** Input Capture Channel 7 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **INT1IE:** External Interrupt 1 Enable bit(1)
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

Note 1: If an external interrupt is enabled, the interrupt input must also be configured to an available RPn or RPIn pin. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

When the RTCC is enabled, it continues to operate with the same clock source (SOSC or LPRC) that was selected prior to entering VBAT mode. There is no provision to switch to a lower power clock source after the mode switch.

Since the loss of VDD is usually an unforeseen event, it is recommended that the contents of the Deep Sleep Semaphore registers be loaded with the data to be retained at an early point in code execution.

10.5.1 VBAT MODE WITH NO RTCC

By disabling RTCC operation during VBAT mode, power consumption is reduced to the lowest of all power-saving modes. In this mode, only the Deep Sleep Semaphore registers are maintained.

10.5.2 WAKE-UP FROM VBAT MODES

When VDD is restored to a device in VBAT mode, it automatically wakes. Wake-up occurs with a POR, after which the device starts executing code from the Reset vector. All SFRs, except the Deep Sleep Semaphores and RTCC registers are reset to their POR values. If the RTCC was not configured to run during VBAT mode, it will remain disabled and RTCC will not run. Wake-up timing is similar to that for a normal POR.

To differentiate a wake-up from VBAT mode from other POR states, check the VBAT status bit (RCON2<0>). If this bit is set while the device is starting to execute the code from Reset vector, it indicates that there has been an exit from VBAT mode. The application must clear the VBAT bit to ensure that future VBAT wake-up events are captured.

If a POR occurs without a power source connected to the VBAT pin, the VBPOR bit (RCON2<1>) is set. If this bit is set on a POR, it indicates that a battery needs to be connected to the VBAT pin.

In addition, if the VBAT power source falls below the level needed for Deep Sleep Semaphore operation while in VBAT mode (e.g., the battery has been drained), the VBPOR bit will be set. VBPOR is also set when the microcontroller is powered up the very first time, even if power is supplied to VBAT.

With VBPOR set, the user should clear it, and the next time, this bit will only set when VDD = 0 and the VBAT pin has gone below level VBTRST.

10.5.3 I/O PINS DURING VBAT MODES

All I/O pins should be maintained at VSS level; no I/O pins should be given VDD (refer to **"Absolute Maximum Ratings"** in **Section 32.0 "Electrical Characteristics"**) during VBAT mode. The only exceptions are the SOSCI and SOSCO pins, which maintain their states if the Secondary Oscillator is being used as the RTCC clock source. It is the user's responsibility to restore the I/O pins to their proper states, using the TRISx and LATx bits, once VDD has been restored.

10.5.4 SAVING CONTEXT DATA WITH THE DSGPRx REGISTERS

As with Deep Sleep mode, all SFRs are reset to their POR values after VDD has been restored. Only the Deep Sleep Semaphore registers are preserved. Applications which require critical data to be saved should save it in DSGPR0 and DSGPR1.

Note:	If the VBAT mode is not used, the recommendation is to connect the VBAT pin to VDD and connect a 0.1 µF capacitor close to the VBAT pin to ground. When the VBAT mode is used (connected to the battery), it is suggested to connect a 0.1 µF capacitor from the VBAT pin to ground. The capacitor should be located very close to the VBAT pin.

The BOR should be enabled for the reliable operation of the VBAT.

REGISTER 11-5: ANSE: PORTE ANALOG FUNCTION SELECTION REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-1	U-0
—	—	—	—	—	—	ANSE9(2)	—
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	U-0	U-0	U-0	U-0
ANSE<7:4>				—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9 **ANSE9:** Analog Function Selection bit(2)
1 = Pin is configured in Analog mode; I/O port read is disabled
0 = Pin is configured in Digital mode; I/O port read is enabled

bit 8 **Unimplemented:** Read as '0'

bit 7-4 **ANSE<7:4>:** Analog Function Selection bits(1)
1 = Pin is configured in Analog mode; I/O port read is disabled
0 = Pin is configured in Digital mode; I/O port read is enabled

bit 3-0 **Unimplemented:** Read as '0'

Note 1: This register is not available in 64-pin and 80-pin devices.
2: This bit is unimplemented on 64-pin devices. In 80-pin devices, this bit needs to be cleared to get digital functionality on RE9.

REGISTER 11-6: ANSG: PORTG ANALOG FUNCTION SELECTION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1
—	—	—	—	—	—	ANSG<9:8>	
bit 15							bit 8

R/W-1	R/W-1	U-0	U-0	U-0	U-0	U-0	U-0
ANSG<7:6>		—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-6 **ANSG<9:6>:** Analog Function Selection bits
1 = Pin is configured in Analog mode; I/O port read is disabled
0 = Pin is configured in Digital mode; I/O port read is enabled

bit 5-0 **Unimplemented:** Read as '0'

16.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to **"Serial Peripheral Interface (SPI)"** (DS39699) in the *"dsPIC33/PIC24 Family Reference Manual"*. The information in this data sheet supersedes the information in the FRM.

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with the SPI and SIOP Motorola® interfaces. All PIC24FJ128GA310 family devices include two SPI modules.

The module supports operation in two buffer modes. In Standard mode, data is shifted through a single serial buffer. In Enhanced Buffer mode, data is shifted through an 8-level FIFO buffer.

Note:	Do not perform Read-Modify-Write operations (such as bit-oriented instructions) on the SPIxBUF register in either Standard or Enhanced Buffer mode.

The module also supports a basic framed SPI protocol while operating in either Master or Slave mode. A total of four framed SPI configurations are supported.

The SPI serial interface consists of four pins:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- $\overline{SS}$x: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPI module can be configured to operate using 2, 3 or 4 pins. In the 3-pin mode, $\overline{SS}$x is not used. In the 2-pin mode, both SDOx and $\overline{SS}$x are not used.

Block diagrams of the module in Standard and Enhanced modes are shown in Figure 16-1 and Figure 16-2.

Note:	In this section, the SPI modules are referred to together as SPIx or separately as SPI1 or SPI2. Special Function Registers will follow a similar notation. For example, SPIxCON1 and SPIxCON2 refer to the control registers for any of the 2 SPI modules.

REGISTER 16-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R-0, HSC	R-0, HSC	R-0, HSC
SPIEN(1)	—	SPISIDL	—	—	SPIBEC2	SPIBEC1	SPIBEC0
bit 15							bit 8

R-0, HSC	R/C-0, HS	R-0, HSC	R/W-0	R/W-0	R/W-0	R-0, HSC	R-0, HSC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown
HSC = Hardware Settable/Clearable bit			

bit 15 **SPIEN:** SPIx Enable bit(1)
- 1 = Enables module and configures SCKx, SDOx, SDIx and $\overline{SS}$x as serial port pins
- 0 = Disables module

bit 14 **Unimplemented:** Read as '0'

bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit
- 1 = Discontinues module operation when device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)

Master mode:
Number of SPI transfers pending.

Slave mode:
Number of SPI transfers unread.

bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)
- 1 = SPIx Shift register is empty and ready to send or receive
- 0 = SPIx Shift register is not empty

bit 6 **SPIROV:** SPIx Receive Overflow Flag bit
- 1 = A new byte/word is completely received and discarded; the user software has not read the previous data in the SPIxBUF register
- 0 = No overflow has occurred

bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)
- 1 = Receive FIFO is empty
- 0 = Receive FIFO is not empty

bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)
- 111 = Interrupt when the SPIx transmit buffer is full (SPITBF bit is set)
- 110 = Interrupt when the last bit is shifted into SPIxSR; as a result, the TX FIFO is empty
- 101 = Interrupt when the last bit is shifted out of SPIxSR; now the transmit is complete
- 100 = Interrupt when one data is shifted into the SPIxSR; as a result, the TX FIFO has one open spot
- 011 = Interrupt when the SPIx receive buffer is full (SPIRBF bit is set)
- 010 = Interrupt when the SPIx receive buffer is 3/4 or more full
- 001 = Interrupt when data is available in the receive buffer (SRMPT bit is set)
- 000 = Interrupt when the last data in the receive buffer is read; as a result, the buffer is empty (SRXMPT bit is set)

Note 1: If SPIEN = 1, these functions must be assigned to available RPn/RPIn pins before use. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

NOTES:

REGISTER 20-9: PADCFG1: PAD CONFIGURATION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	PMPTTL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as ‘0’

bit 0 **PMPTTL:** EPMP Module TTL Input Buffer Select bit
1 = EPMP module inputs (PMDx, PMCS1) use TTL input buffers
0 = EPMP module inputs use Schmitt Trigger input buffers

22.2 RTCC Module Registers

The RTCC module registers are organized into three categories:

- RTCC Control Registers
- RTCC Value Registers
- Alarm Value Registers

22.2.1 REGISTER MAPPING

To limit the register interface, the RTCC Timer and Alarm Time registers are accessed through corresponding register pointers. The RTCC Value register window (RTCVALH and RTCVALL) uses the RTCPTR bits (RCFGCAL<9:8>) to select the desired Timer register pair (see Table 22-1).

By writing the RTCVALH byte, the RTCC Pointer value, the RTCPTR<1:0> bits decrement by one until they reach '00'. Once they reach '00', the MINUTES and SECONDS value will be accessible through RTCVALH and RTCVALL until the pointer value is manually changed.

TABLE 22-1: RTCVAL REGISTER MAPPING

RTCPTR<1:0>	RTCC Value Register Window	
	RTCVAL<15:8>	RTCVAL<7:0>
00	MINUTES	SECONDS
01	WEEKDAY	HOURS
10	MONTH	DAY
11	—	YEAR

The Alarm Value register window (ALRMVALH and ALRMVALL) uses the ALRMPTR bits (ALCFGRPT<9:8>) to select the desired Alarm register pair (see Table 22-2).

By writing the ALRMVALH byte, the Alarm Pointer value, ALRMPTR<1:0> bits, decrement by one until they reach '00'. Once they reach '00', the ALRMMIN and ALRMSEC value will be accessible through ALRMVALH and ALRMVALL until the pointer value is manually changed.

TABLE 22-2: ALRMVAL REGISTER MAPPING

ALRMPTR <1:0>	Alarm Value Register Window	
	ALRMVAL<15:8>	ALRMVAL<7:0>
00	ALRMMIN	ALRMSEC
01	ALRMWD	ALRMHR
10	ALRMMNTH	ALRMDAY
11	—	—

Considering that the 16-bit core does not distinguish between 8-bit and 16-bit read operations, the user must be aware that when reading either the ALRMVALH or ALRMVALL bytes, the ALRMPTR<1:0> value will be decremented. The same applies to the RTCVALH or RTCVALL bytes with the RTCPTR<1:0> being decremented.

Note: This only applies to read operations and not write operations.

22.2.2 WRITE LOCK

In order to perform a write to any of the RTCC Timer registers, the RTCWREN bit (RCFGCAL1<13>) must be set (see Example 22-1).

Note: To avoid accidental writes to the timer, it is recommended that the RTCWREN bit (RCFGCAL1<13>) is kept clear at any other time. For the RTCWREN bit to be set, there is only one instruction cycle time window allowed between the 55h/AA sequence and the setting of RTCWREN; therefore, it is recommended that code follow the procedure in Example 22-1.

22.2.3 SELECTING RTCC CLOCK SOURCE

The clock source for the RTCC module can be selected using the RTCLK<1:0> bits in the RTCPWC register. When the bits are set to '00', the Secondary Oscillator (SOSC) is used as the reference clock and when the bits are '01', LPRC is used as the reference clock. When RTCLK<1:0> = 10 and 11, the external power line (50 Hz and 60 Hz) is used as the clock source.

EXAMPLE 22-1: SETTING THE RTCWREN BIT

```
asm volatile("push w7");
asm volatile("push w8");
asm volatile("disi #5");
asm volatile("mov #0x55, w7");
asm volatile("mov w7, _NVMKEY");
asm volatile("mov #0xAA, w8");
asm volatile("mov w8, _NVMKEY");
asm volatile("bset _RCFGCAL1, #13"); //set the RTCWREN bit
asm volatile("pop w8");
asm volatile("pop w7");
```

REGISTER 22-1: RCFGCAL: RTCC CALIBRATION/CONFIGURATION REGISTER(1) (CONTINUED)

bit 7-0 **CAL<7:0>:** RTC Drift Calibration bits

01111111 = Maximum positive adjustment; adds 127 RTC clock pulses every 15 seconds

.

.

.

01111111 = Minimum positive adjustment; adds 1 RTC clock pulse every 15 seconds

00000000 = No adjustment

11111111 = Minimum negative adjustment; subtracts 1 RTC clock pulse every 15 seconds

.

.

.

10000000 = Maximum negative adjustment; subtracts 128 RTC clock pulses every 15 seconds

Note 1: The RCFGCAL register is only affected by a POR.

2: A write to the RTCEN bit is only allowed when RTCWREN = 1.

3: This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

REGISTER 24-6: AD1CHS: ADC1 SAMPLE SELECT REGISTER (CONTINUED)

bit 7-5 **CH0NA<2:0>:** Sample A Channel 0 Negative Input Select bits
Same definitions as for CHONB<2:0>.

bit 4-0 **CH0SA<4:0>:** Sample A Channel 0 Positive Input Select bits
Same definitions as for CHOSB<4:0>.

Note 1: These input channels do not have corresponding memory-mapped result buffers.
2: These channels are implemented in 100-pin devices only.

REGISTER 24-7: ANCFG: ADC BAND GAP REFERENCE CONFIGURATION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	VBG6EN	VBG2EN	VBGEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2 **VBG6EN:** ADC Input V_{BG}/6 Enable bit
1 = Band gap voltage, divided by six reference (V_{BG}/6), is enabled
0 = Band gap, divided by six reference (V_{BG}/6), is disabled

bit 1 **VBG2EN:** ADC Input V_{BG}/2 Enable bit
1 = Band gap voltage, divided by two reference (V_{BG}/2), is enabled
0 = Band gap, divided by two reference (V_{BG}/2), is disabled

bit 0 **VBGEN:** ADC Input V_{BG} Enable bit
1 = Band gap voltage reference (V_{BG}) is enabled
0 = Band gap reference (V_{BG}) is disabled

FIGURE 24-5: 10-BIT ADC TRANSFER FUNCTION

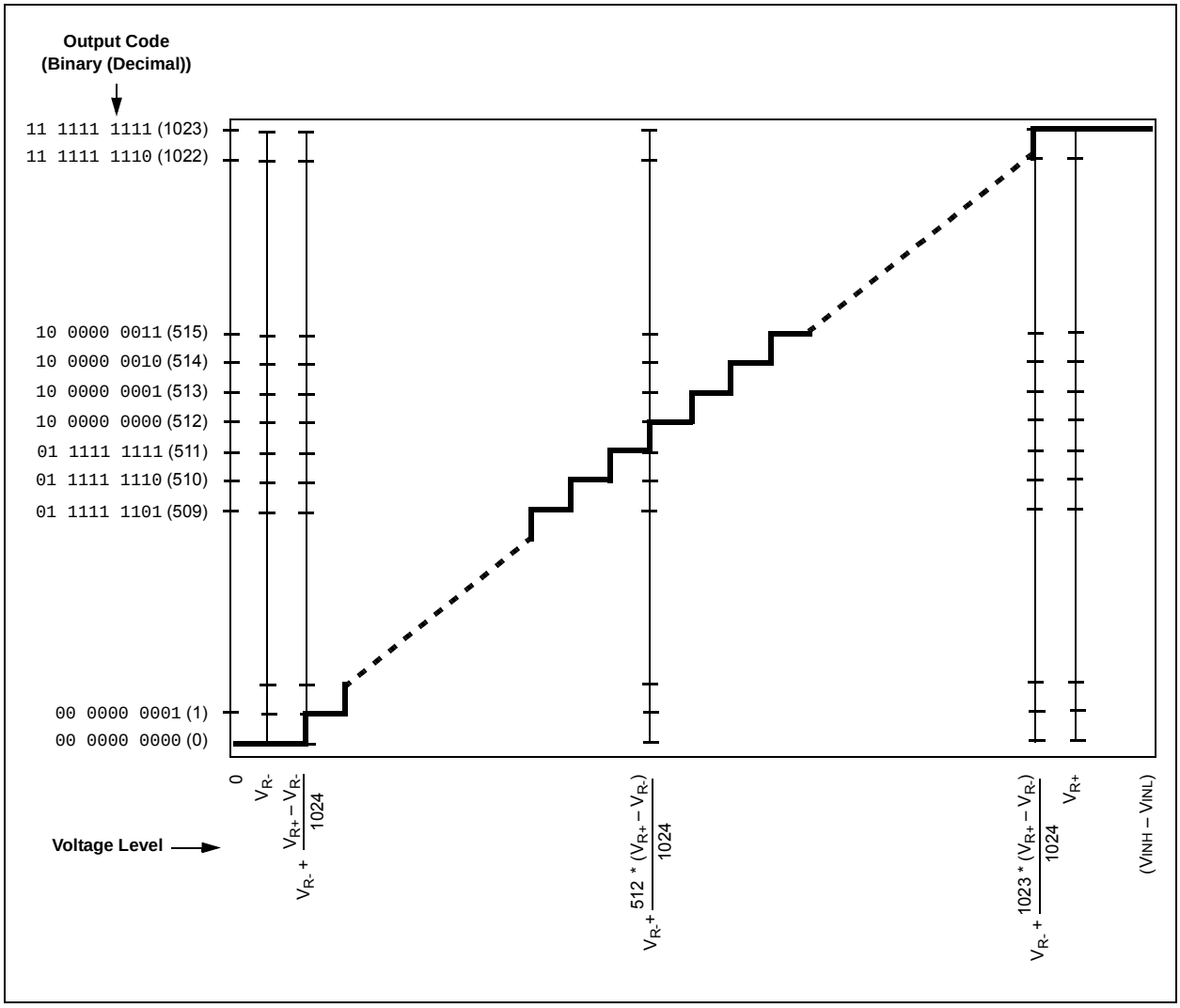


TABLE 31-2: INSTRUCTION SET OVERVIEW

Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
ADD	ADD	f	f = f + WREG	1	1	C, DC, N, OV, Z
	ADD	f,WREG	WREG = f + WREG	1	1	C, DC, N, OV, Z
	ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C, DC, N, OV, Z
	ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C, DC, N, OV, Z
	ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C, DC, N, OV, Z
ADDC	ADDC	f	f = f + WREG + (C)	1	1	C, DC, N, OV, Z
	ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C, DC, N, OV, Z
	ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C, DC, N, OV, Z
	ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C, DC, N, OV, Z
	ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C, DC, N, OV, Z
AND	AND	f	f = f .AND. WREG	1	1	N, Z
	AND	f,WREG	WREG = f .AND. WREG	1	1	N, Z
	AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N, Z
	AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N, Z
	AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N, Z
ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C, N, OV, Z
	ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C, N, OV, Z
	ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C, N, OV, Z
	ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N, Z
	ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N, Z
BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
	BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
BRA	BRA	C,Expr	Branch if Carry	1	1 (2)	None
	BRA	GE,Expr	Branch if Greater than or Equal	1	1 (2)	None
	BRA	GEU,Expr	Branch if Unsigned Greater than or Equal	1	1 (2)	None
	BRA	GT,Expr	Branch if Greater than	1	1 (2)	None
	BRA	GTU,Expr	Branch if Unsigned Greater than	1	1 (2)	None
	BRA	LE,Expr	Branch if Less than or Equal	1	1 (2)	None
	BRA	LEU,Expr	Branch if Unsigned Less than or Equal	1	1 (2)	None
	BRA	LT,Expr	Branch if Less than	1	1 (2)	None
	BRA	LTU,Expr	Branch if Unsigned Less than	1	1 (2)	None
	BRA	N,Expr	Branch if Negative	1	1 (2)	None
	BRA	NC,Expr	Branch if Not Carry	1	1 (2)	None
	BRA	NN,Expr	Branch if Not Negative	1	1 (2)	None
	BRA	NOV,Expr	Branch if Not Overflow	1	1 (2)	None
	BRA	NZ,Expr	Branch if Not Zero	1	1 (2)	None
	BRA	OV,Expr	Branch if Overflow	1	1 (2)	None
	BRA	Expr	Branch Unconditionally	1	2	None
	BRA	Z,Expr	Branch if Zero	1	1 (2)	None
	BRA	Wn	Computed Branch	1	2	None
BSET	BSET	f,#bit4	Bit Set f	1	1	None
	BSET	Ws,#bit4	Bit Set Ws	1	1	None
BSW	BSW.C	Ws,Wb	Write C bit to Ws<Wb>	1	1	None
	BSW.Z	Ws,Wb	Write Z bit to Ws<Wb>	1	1	None
BTG	BTG	f,#bit4	Bit Toggle f	1	1	None
	BTG	Ws,#bit4	Bit Toggle Ws	1	1	None
BTSC	BTSC	f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
	BTSC	Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None

TABLE 32-7: DC CHARACTERISTICS: ΔCURRENT (BOR, WDT, DSBOR, DSWDT, LCD)

DC CHARACTERISTICS			Standard Operating Conditions: 2V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Operating Temperature**	**VDD**	**Conditions**
Incremental Current Brown-out Reset (ΔBOR)(2)						
DC20	3.1	5	μA	-40°C to +85°C	2.0V	ΔBOR(2)
	4.3	6	μA	-40°C to +85°C	3.3V	
Incremental Current Watch Dog Timer (ΔWDT)(2)						
DC71	0.8	1.5	μA	-40°C to +85°C	2.0V	ΔWDT(2)
	0.8	1.5	μA	-40°C to +85°C	3.3V	
Incremental Current HLVD (ΔHLVD)(2)						
DC75	5.7	15	μA	-40°C to +85°C	2.0V	ΔHLVD(2)
	5.7	15	μA	-40°C to +85°C	3.3V	
Incremental Current Real-Time Clock and Calendar (RTCC)(2)						
DC77	0.4	1	μA	-40°C to +85°C	2.0V	ΔRTCC(2), RTCC with SOSC
	0.4	1	μA	-40°C to +85°C	3.3V	
Incremental Current Real-Time Clock and Calendar (RTCC)(2)						
DC77a	0.4	1	μA	-40°C to +85°C	2.0V	ΔRTCC(2), RTCC with LPRC
	0.4	1	μA	-40°C to +85°C	3.3V	
Incremental Current Deep Sleep BOR (Δ DSBOR)(2)						
DC81	0.07	0.3	μA	-40°C to +85°C	2.0V	ΔDeep Sleep BOR(2)
	0.07	0.3	μA	-40°C to +85°C	3.3V	
Incremental Current Deep Sleep Watchdog Timer Reset (Δ DSWDT)(2)						
DC80	0.27	0.4	μA	-40°C to +85°C	2.0V	ΔDeep Sleep WDT(2)
	0.27	0.4	μA	-40°C to +85°C	3.3V	
Incremental Current LCD (Δ LCD)(2)						
	0.8	3	μA	-40°C to +85°C	3.3V	ΔLCD External/Internal(2,3), 1/8 MUX, 1/3 Bias
DC90	20	30	μA	-40°C to +85°C	2.0V	ΔLCD Charge Pump(2,4), 1/8 MUX, 1/3 Bias
	24	40	μA	-40°C to +85°C	3.3V	
VBAT ADC Monitor(5)						
DC91	1.5	—	μA	-40°C to +85°C	3.3V	VBAT = 2V
	4	—	μA	-40°C to +85°C	3.3V	VBAT = 3.3V

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated. IPD is measured with all peripherals and clocks (PMD) shut down; all the ports are made output and driven low.

2: Incremental current while the module is enabled and running.

3: LCD is enabled and running; no glass is connected; the resistor ladder current is not included.

4: LCD is enabled and running; no glass is connected.

5: The ADC channel is connected to the VBAT pin internally; this is the current during ADC VBAT operation.

FIGURE 32-15: SPIx MODULE MASTER MODE TIMING CHARACTERISTICS (CKE = 1)

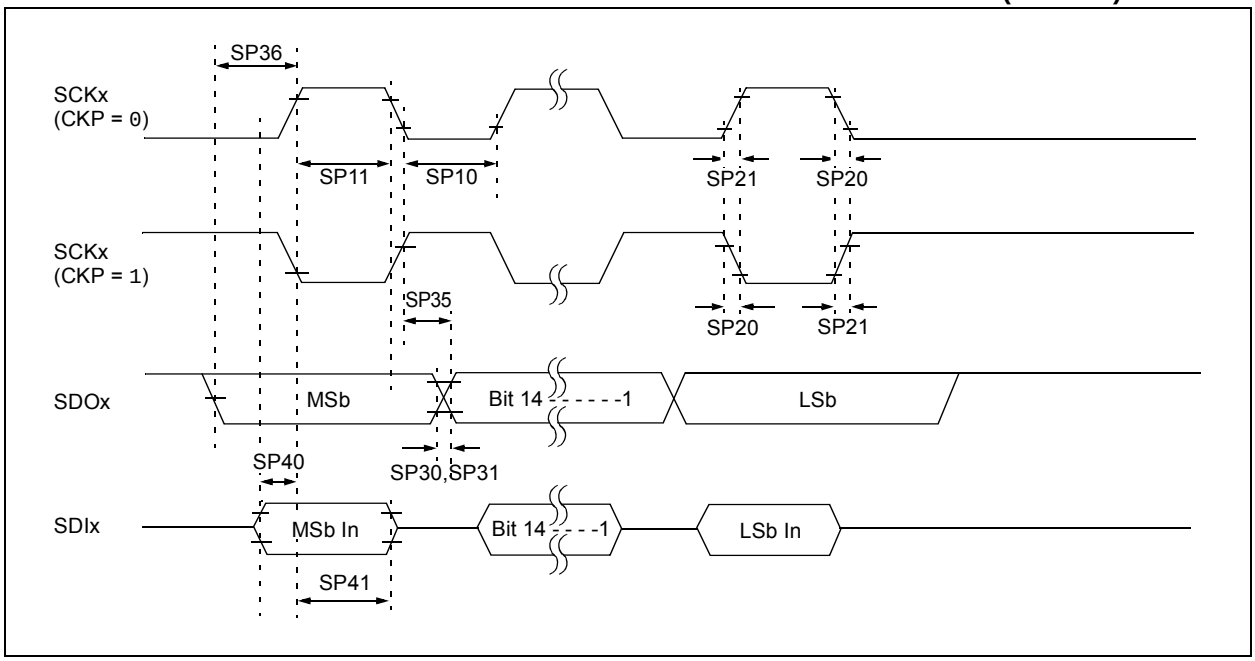


TABLE 32-35: SPIx MODULE MASTER MODE TIMING REQUIREMENTS (CKE = 1)

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time(2)	TCY/2	—	—	ns	
SP11	TscH	SCKx Output High Time(2)	TCY/2	—	—	ns	
SP20	TscF	SCKx Output Fall Time(3)	—	10	25	ns	
SP21	TscR	SCKx Output Rise Time(3)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(3)	—	10	25	ns	
SP31	TdoR	SDOx Data Output Rise Time(3)	—	10	25	ns	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	

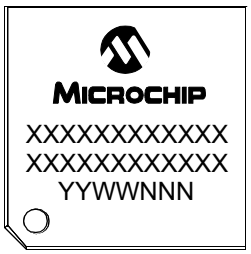
Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

3: Assumes 50 pF load on all SPIx pins.

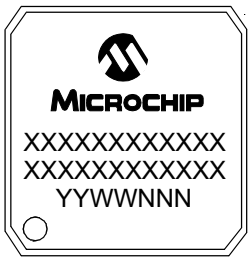
33.2 Package Marking Information

100-Lead TQFP (12x12x1 mm)



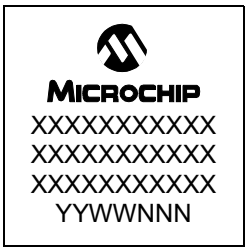
Example

100-Lead TQFP (14x14x1mm)



Example

121-BGA (10x10x1.1 mm)



Example